



Material Content Data Sheet



Sales Product Name		2EDL05I06PJ		Issued		29. August 2013		
MA#		MA001136736						
Package		PG-DSO-14-49		Weight*		138.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.952	0.69	0.69	6858	6858
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		103	
	non noble metal	zinc	7440-66-6	0.057	0.04		414	
	non noble metal	iron	7439-89-6	1.150	0.83		8280	
wire	non noble metal	copper	7440-50-8	46.675	33.62	34.50	336194	344991
	noble metal	gold	7440-57-5	0.228	0.16	0.16	1644	1644
encapsulation	organic material	carbon black	1333-86-4	0.175	0.13		1263	
	plastics	epoxy resin	-	9.470	6.82		68209	
	inorganic material	silicondioxide	60676-86-0	78.036	56.21	63.16	562090	631562
leadfinish	non noble metal	tin	7440-31-5	1.226	0.88	0.88	8832	8832
plating	noble metal	silver	7440-22-4	0.307	0.22	0.22	2208	2208
glue	plastics	acrylic resin	-	0.119	0.09		859	
	noble metal	silver	7440-22-4	0.423	0.30	0.39	3046	3905
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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